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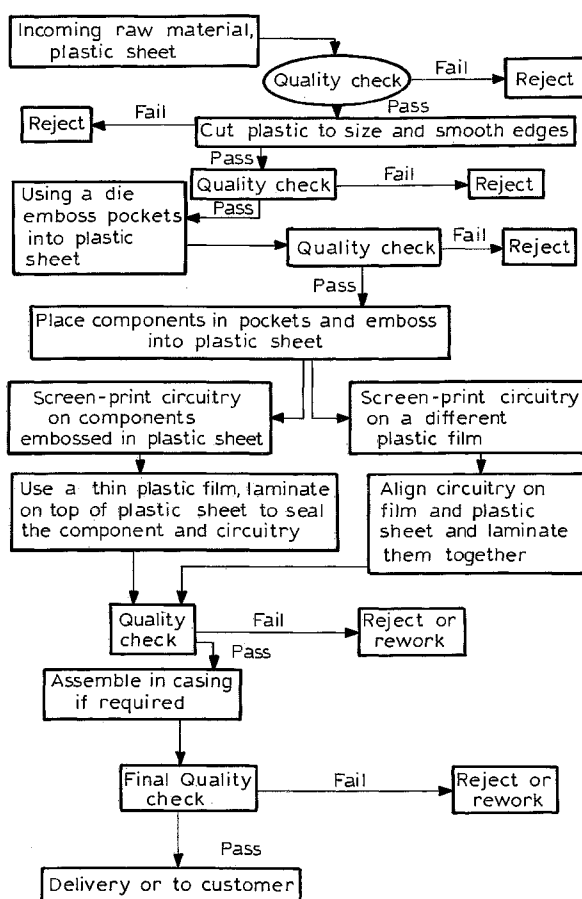
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(54) Title: FABRICATION OF ELECTRONIC COMPONENTS IN PLASTIC



(57) Abstract: A method of forming electronic components in which a thermoplastic substrate is embossed to create a recess for electronic components; the electronic component is placed in the recess; electrical connections and circuitry are deposited over the components on the thermoplastic substrate; and a cover sheet of thermoplastic material is bonded over the circuitry. The process may also be carried out in reverse order. The apparatus used consists of a hot embossing machine having a former shaped for each particular circuit to be assembled; a pick and place machine with standard reel loading of components; and a screen printer for printing the conductive ink circuitry or a station for adhering conductive tape or preprinted film.

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